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PATENT

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Date

January 4, 2001

Cheryl Ammerlahn

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Tongbi Jiang

Attorney Docket No.: 500182.01 (660073.774)

Serial No. : 09/365,356

Group Art Unit : 2813

Filed : July 30, 1999

Examiner : Nema O. Berezny

Title : METHOD AND STRUCTURE FOR MANUFACTURING IMPROVED YIELD SEMICONDUCTOR PACKAGED DEVICES

Box Non-Fee Amendment
Commissioner of Patents
Washington, DC 20231

AMENDMENT

Sir:

In response to the Office Action dated October 4, 2000, please amend the application as follows:

In the Claims:

Please add new claims 38-49 as follows:

- 38. A semiconductor device package, comprising:
- a semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated;
 - an interposer having a die attach surface and at least one electrically conductive interconnect electrically coupled to at least one bond pad of the semiconductor die; and

#8

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FACSIMILE COVER SHEET

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Date: April 26, 2001

To: Nema O. Berezny, Examiner
Charles Bowers, Jr., Supervisory Examiner
U.S. Patent and Trademark Office

Fax: (703) 308-7722
Phone: (703) 308-3445

Re: Dorsey Docket No.: 660073.774
(500182.01)
U.S. Application No. 09/365,356,
filed July 30, 1999

From: Cheryl Ammerlahn

Telephone: (206) 903-5421

Total Number of Pages: 8 (including this cover sheet)

With reference to the above-identified application, attached is the response to the Office action dated October 4, 2000 which we mailed to the Patent and Trademark Office on January 4, 2001. Also attached is the return receipt postcard identifying the mailing which we enclosed with the response.

Please telephone me at 206-903-5421 when a determination has been made regarding the status of the application.

Thank you.

- Cheryl Ammerlahn

Original ____ will be sent (if requested) X will not be sent.

PLEASE CONTACT Cheryl Ammerlahn AT (206) 903-5421
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500182.01 (650073.774)
KNE:c

Box Non-Fec Amendment
Commissioner of Patents
Washington, DC 20231

SENT: January 4, 2001

Kindly acknowledge receipt of the below-listed documents by placing
your receiving stamp hereon and mailing:

Amendment; in re: Tongbi Jiang, USAN 09/365,356, filed July 30, 1999, for METHOD
AND STRUCTURE FOR MANUFACTURING IMPROVED YIELD
SEMICONDUCTOR PACKAGED DEVICES.

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